

AP 3723



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PATENT

Group 3700

Art Unit: 3723

Examiner: Eley, T.

Applicant : D. Bennett et al.

Serial No.: 09/003,315

Filed : January 6, 1998

Title : POLISHING PAD HAVING A GROOVED PATTERN FOR USE IN A CHEMICAL MECHANICAL POLISHING APPARATUS

Handwritten notes: #91amat3, 6/20/99, E. B. B. B.

AMENDMENT

In response to the Office Action dated March 8, 1999, please amend application Serial Number 09/003,315, as follows.

In the Claims:

Please cancel claims 14-42.

104. (Amended) A polishing pad to polish a substrate in a chemical mechanical polishing apparatus, comprising:

a first polishing region having a first plurality of substantially circular concentric grooves with a first width and a first pitch;

a second polishing region surrounding the first polishing region and having a second plurality of substantially circular concentric grooves with a second width and a second pitch;

a third polishing region surrounding the second polishing region and having a third plurality of substantially circular concentric grooves with a third width and a third pitch;

wherein at least one of the second width and second pitch differs from the first width and first pitch;

Date of Deposit June 7, 1999

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated above and is addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

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